

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT3413571

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
SO YOUNG KWON	06/25/2015
JIN KYU KIM	06/25/2015
SEUNG YOUB BANG	06/25/2015
EUN JU LEE	06/25/2015
SANG KYUN IM	06/25/2015
KI YON LEE	06/25/2015
SUK MIN JUN	06/25/2015
SUNG CHUL CHOI	06/25/2015
RECEIVING PARTY DATA	
Name:	CHEIL INDUSTRIES INC.
Street Address:	290 GONGDAN-DONG
Internal Address:	GUMI-SI, GYEONGSANGBUK-DO
City:	GUMI-SI
State/Country:	KOREA, REPUBLIC OF
Postal Code:	730-710
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	14655569
CORRESPONDENCE DATA	
Fax Number:	(704)945-6735
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	704-945-6700
Email:	docket@ahpapatent.com
Correspondent Name:	MELISSA B. PENDLETON
Address Line 1:	11610 N. COMMUNITY HOUSE ROAD
Address Line 2:	SUITE 200
Address Line 4:	CHARLOTTE, NORTH CAROLINA 28277
ATTORNEY DOCKET NUMBER:	1224.179
NAME OF SUBMITTER:	MELISSA B. PENDLETON

PATENT

SIGNATURE:	/Melissa B. Pendleton/
DATE SIGNED:	06/25/2015
Total Attachments: 5 source=AssignmentUSPTO#page1.tif source=AssignmentUSPTO#page2.tif source=AssignmentUSPTO#page3.tif source=AssignmentUSPTO#page4.tif source=AssignmentUSPTO#page5.tif	

RECORDATION FORM COVER SHEET PATENTS ONLY

To the Director of the U.S. Patent and Trademark Office: Please record the attached documents or the new address(es) below.

1. Name of conveying party(ies)

- 1) SO YOUNG KWON
- 2) JIN KYU KIM
- 3) SEUNG YOUB BANG
- 4) EUN JU LEE
- 5) SANG KYUN IM
- 6) KI YON LEE
- 7) SUK MIN JUN
- 8) SUNG CHUL CHOI

Additional name(s) of conveying party(ies) attached? Yes No

2. Name and address of receiving party(ies)

Name: Cheil Industries Inc.

Internal Address: _____

Street Address: 290 Gongdan-dong

City: Gumi-si

State: Gyeongsangbuk-do

Country: South Korea Zip: 730-710

Additional name(s) & address(es) attached? Yes No

3. Nature of conveyance/Execution Date(s):

Execution Date(s) June 25, 2015

- Assignment
- Merger
- Security Agreement
- Change of Name
- Joint Research Agreement
- Government Interest Assignment
- Executive Order 9424, Confirmatory License
- Other _____

4. Application or patent number(s):

This document is being filed together with a new application.

A. Patent Application No.(s)

14/655,569

B. Patent No.(s)

Additional numbers attached? Yes No

5. Name and address to whom correspondence concerning document should be mailed:

Name: Additon, Higgins & Pendleton, P.A.

Internal Address: _____

Street Address: 11610 N. Community House Road, Suite 200

City: Charlotte

State: NC Zip: 28277-2199

Phone Number: 704-945-6700

Fax Number: 704-945-6735

Email Address: _____

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 1.21(h) & 3.41) \$ _____

- Authorized to be charged by credit card
- Authorized to be charged to deposit account
- Enclosed
- None required (government interest not affecting title)

8. Payment Information

a. Credit Card Last 4 Numbers _____
Expiration Date _____

b. Deposit Account Number _____

Authorized User Name _____

9. Signature: /Melissa B. Pendleton/

June 25, 2015

Melissa B. Pendleton

Signature

Date

Name of Person Signing

Total number of pages including cover sheet, attachments, and documents: 5

Documents to be recorded (including cover sheet) should be faxed to (571) 273-0140, or mailed to:
Mail Stop Assignment Recordation Services, Director of the USPTO, P.O. Box 1450, Alexandria, V.A. 22313-1450

ASSIGNMENT

WHEREAS, I, So Young KWON, a Korean citizen, with a mailing address of 332-2 Gocheon-dong, Uiwang-si, Gyeonggi-do, Republic of Korea; Jin Kyu KIM, a Korean citizen, with a mailing address of 332-2 Gocheon-dong, Uiwang-si, Gyeonggi-do, Republic of Korea; Seung Youb BANG, a Korean citizen, with a mailing address of 332-2 Gocheon-dong, Uiwang-si, Gyeonggi-do, Republic of Korea; Eun Ju LEE, a Korean citizen, with a mailing address of 332-2 Gocheon-dong, Uiwang-si, Gyeonggi-do, Republic of Korea; Sang Kyun IM, a Korean citizen, with a mailing address of 332-2 Gocheon-dong, Uiwang-si, Gyeonggi-do, Republic of Korea; Ki Yon LEE, a Korean citizen, with a mailing address of 332-2 Gocheon-dong, Uiwang-si, Gyeonggi-do, Republic of Korea; Suk Min JUN, a Korean citizen, with a mailing address of 332-2 Gocheon-dong, Uiwang-si, Gyeonggi-do, Republic of Korea; and Sung Chul CHOI, a Korean citizen, with a mailing address of 332-2 Gocheon-dong, Uiwang-si, Gyeonggi-do, Republic of Korea; (hereinafter referred to as "ASSIGNOR"), am a joint inventor of certain new and useful improvements (hereinafter collectively referred to as "INVENTION") in *Polyamide Resin, Preparation Method Therefor, and Molded Product Including Same*, for which an application for United States Letters Patent is being filed concurrently herewith and which application claims priority from an International Application filed on March 27, 2013, under Serial No. PCT/KR2013/002528; and a Korean application filed on December 28, 2012, under Serial No. 10-2012-0157673, all applications listed above being hereinafter referred to as the "APPLICATION"; and

WHEREAS, Cheil Industries Inc., a Korean corporation (hereinafter referred to as "ASSIGNEE"), having a principal place of business at 290 Gongdan-dong, Gumi-si, Gyeongsangbuk-do 730-710, Republic of Korea, has acquired the equitable right, title,

and interest—and is desirous of acquiring any remaining right, title, and interest—in and to said INVENTION as described in said APPLICATION, and in and to any and all Letters Patent that shall be granted with respect to said INVENTION in the United States of America and all foreign countries;

NOW, THEREFORE, be it known that for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, I, the ASSIGNOR, have sold, assigned, transferred, and conveyed unto said ASSIGNEE, its successors and assigns, my equitable right, title, and interest—and by these presents do hereby sell, assign, transfer, and convey unto said ASSIGNEE, its successors and assigns any remaining right, title, and interest—in and to said INVENTION and APPLICATION, in and to any and all continuations, continuations-in-part, or divisions thereof, and in and to any and all Letters Patent of the United States of America and all foreign countries or reissues, reexaminations, or extensions thereof that may be granted therefore or thereon, for the full term for which said Letters Patent may be granted, together with the right to claim the priority of said APPLICATION in all foreign countries in accordance with international treaties and conventions, the same to be held and enjoyed by said ASSIGNEE, its successors and assigns, as fully and entirely as the same would have been held and enjoyed by me if an assignment and sale had not been made.

I acknowledge that at the time the INVENTION was made, the INVENTION was subject to an obligation of assignment to said ASSIGNEE. I further acknowledge that said ASSIGNEE has the sole right to determine patent prosecution strategies with respect to said INVENTION and all corresponding applications, and hereby request that Letters Patent be issued in accordance with this assignment.

I further covenant and agree to bind my heirs, legal representatives, and assigns, promptly to communicate to said ASSIGNEE or its representatives any facts known to me relating to said INVENTION, to testify in any interference or legal proceedings involving said INVENTION, to execute any additional papers that may be requested to confirm the right of the ASSIGNEE, its representatives, successors or assigns to secure patent or similar protection for said INVENTION in all countries and to vest in the ASSIGNEE complete title to said INVENTION and Letters Patent, without further compensation, but at the expense of said ASSIGNEE, its successors, assigns and other legal representatives.

As the below named inventor, I hereby declare:

The application for United States Letters Patent being filed concurrently herewith was made or authorized to be made by me.

I believe that I am the original or an original joint inventor of a claimed invention in the application.

I hereby acknowledge that any willful false statement made in the declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

IN WITNESS WHEREOF, I have hereunto signed my name on the day and year set forth below.

6/25, 2015

김영준
So Young KWON

6/25, 2015

김진규
Jin Kyu KIM

6/25, 2015

방승엽
Seung Youb BANG

6/25, 2015

Eun Ju
Eun Ju LEE

6/25, 2015

임상균
Sang Kyun IM

6/28, 2015

이윤리
Ki Yon LEE

6/25, 2015

수민준
Suk Min JUN

6/25, 2015

성철최
Sung Chul CHOI